

Layer	Stack up	Supplier	Supplier Description	Description	Type	Tg	εr	Base Thickness	Processed Thickness
1		Electra Polymers		Liquid PhotoImageable Mask	SolderMask			4.000	
		Circuitfoil		Copper Foil	Copper			0.018	0.038
2		Shanghai Nanya	NY2150	Prepreg1080	Dielectric	150.000	4.200	0.070	0.057
		Shanghai Nanya	NY2150	Prepreg1080	Dielectric	150.000	4.200	0.070	0.057
3		Shanghai Nanya	NY2150	NY2150 Core	FR4	150.000	4.200	0.200	0.200
		Shanghai Nanya	NY2150	Prepreg1080	Dielectric	150.000	4.200	0.035	0.035
4		Shanghai Nanya	NY2150	Prepreg1080	Dielectric	150.000	4.200	0.070	0.044
		Shanghai Nanya	NY2150	Prepreg1080	Dielectric	150.000	4.200	0.070	0.044
5		Shanghai Nanya	NY2150	NY2150 Core	FR4	150.000	4.200	0.200	0.200
		Shanghai Nanya	NY2150	Prepreg1080	Dielectric	150.000	4.200	0.035	0.035
6		Shanghai Nanya	NY2150	Prepreg1080	Dielectric	150.000	4.200	0.070	0.057
		Shanghai Nanya	NY2150	Prepreg1080	Dielectric	150.000	4.200	0.070	0.057
		Circuitfoil		Copper Foil	Copper			0.018	0.038
		Electra Polymers		Liquid PhotoImageable Mask	SolderMask			4.000	

0.93

Copper Thickness = 0.216 | Dielectric Thickness = 0.715 | Solder Mask Thickness = 0.050 | Stack Up Thickness = 0.931 | Stack Up Thickness with Soldermask = 0.981 | Stack Up Cost = 34.00 |

Drill Image	1st Layer	2nd Layer	Column Position
	1	6	1

Notes

StackName: Standard 1.0 Mlb4	Version:	Revision:	Modification:	Date of Revision:	Editor	Page 1/1
Date: 2017/05/03	Associated Documents:					
Author: Henoc N.						
Department: Tech						
Site: Diep River						